

34. (New) A method of manufacturing a semiconductor device, comprising steps of:
forming a pattern comprising a light-shielding film over a front side of a
light transmissive substrate;

forming a photosensitive film over said pattern;
preparing a reflecting means located opposite to said photosensitive film;
preparing a light source for emitting a light; and
exposing said photosensitive film by irradiating it from a back side of said
substrate with said light emitted from said light source while using said pattern as a mask
wherein a reflecting means reflects a light passing through said photosensitive film, thereby said
photosensitive film is irradiated from the front side of said substrate with the light and is
exposed.

35. (New) A method of manufacturing a semiconductor device, comprising steps of:
forming a pattern comprising a light-shielding film over a front side of a light transmissive
substrate;

forming a photosensitive film over said pattern;
preparing a reflecting means located opposite to said photosensitive film;
preparing a light source for emitting a light; and
exposing said photosensitive film by irradiating it from a back side of said
substrate with said light emitted from said light source while using said pattern as a mask
wherein a reflecting means reflects a light passing through said photosensitive film, thereby said
photosensitive film is irradiated from the front side of said substrate with the light and is
exposed.


36. (New) A method according to claim 35, wherein a shape of the photosensitive film over said pattern corresponds to a reduced shape of said pattern comprising the light-shielding film.

Please discharge Deposit Account No. 50-1039 for any fee due for this amendment.

Favorable consideration is earnestly solicited.

Respectfully submitted,

Dated: November 1, 2001


Mark J. Murphy
Registration No. 34, 225

COOK, ALEX, McFARRON, MANZO,
CUMMINGS & MEHLER, LTD.
200 West Adams Street
Suite 2850
Chicago, Illinois 60606
(312) 236-8500